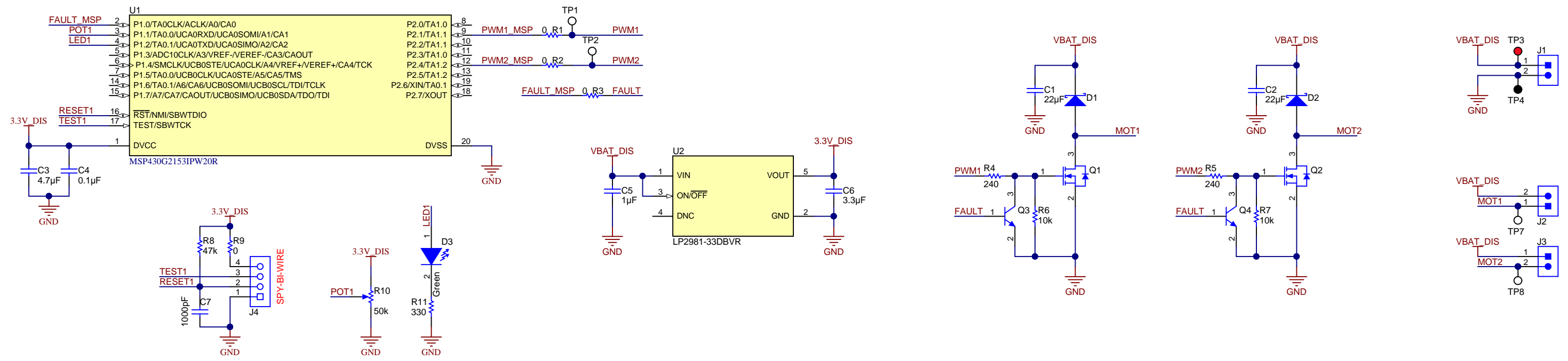
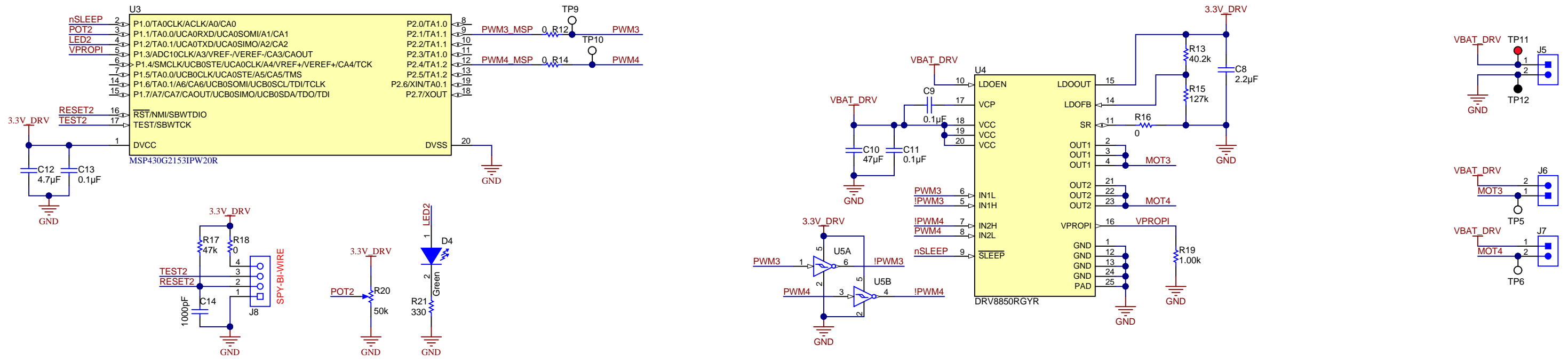


Discrete Implementation



DRV8850 Implementation



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TID #: TIDA-01162	Project Title: TIDA-01162	
Number: TIDA-01162	Rev: E1	Sheet Title:
SVN Rev: Version control disabled	Assembly Variant: 001	Sheet: 2 of 3
Drawn By:	File: TIDA-01162_SCH.SchDoc	Size: B
Engineer: Nick Oborny	Contact: http://www.ti.com/support	



DNP FID1 DNP FID2 DNP FID3

PCB Number: TIDA-01162
PCB Rev: E1

PCB LOGO
Texas Instruments


PCB LOGO
Pb-Free Symbol

ZZ1
Label Assembly Note
This Assembly Note is for PCB labels only

ZZ2
Assembly Note
These assemblies are ESD sensitive, ESD precautions shall be observed.

ZZ3
Assembly Note
These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ4
Assembly Note
These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

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Number: TIDA-01162	Rev: E1	Sheet Title:	
SVN Rev: Version control disabled	Assembly Variant: 001	Sheet: 3 of 3	
Drawn By:	File: TIDA-01162_HW.SchDoc	Size: B	
Engineer: Nick Oborny	Contact: http://www.ti.com/support		

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